



16-bit Constant-Current LED Driver with Modeless™ Error Detection

Product Description

The SCT2027 is a serial-interfaced 16-bit constant-current sinker with error detection designed for LED displays and LED lighting applications. In applications, an external resistor is used to adjust the full-scale output current from 5mA up to 90mA. The serial data are shifted into 16-bit shift register by clock signal. Input data appear at the SDO output 16 clock cycles later to allow cascading of multiple SCT2027s. The latch-enable input, LA/, loads the 16 bits data of shift register into a 16-bit latch to determine which LEDs are on and off. The output enable input, OE/ gates all 16 outputs on and off, and is fast enough to be used as PWM input for the LED intensity control.

The SCT2027 combines the SCT2024/6 with Modeless™ technique to detect open-load and shorted-load errors while driving the LEDs without mode switching*. With the pin-to-pin compatible design, all the LED display or lighting systems can be upgraded to perform the on-the-fly error-detection functions simply by replacing all the SCT2024/6s with SCT2027s directly. Also, by the Modeless™ technique, the software and hardware works well without reworks between systems of the SCT2024/6 and SCT2027.

During operations, the SCT2027 takes only 200ns to generate error status codes after the rising edge of LA/. The error status codes saved in the shift register can be shifted out via SDO bit-by-bit along with CLK, at the same time the new serial data can be shifted into SCT2027 via SDI. By comparing the display data with error status codes, the system control unit can read the error status to determine whether or not the LEDs are properly lit. If the input display signals are inconsistent with the corresponding output status code, the corresponding LEDs are determined to have been stuck open or short.

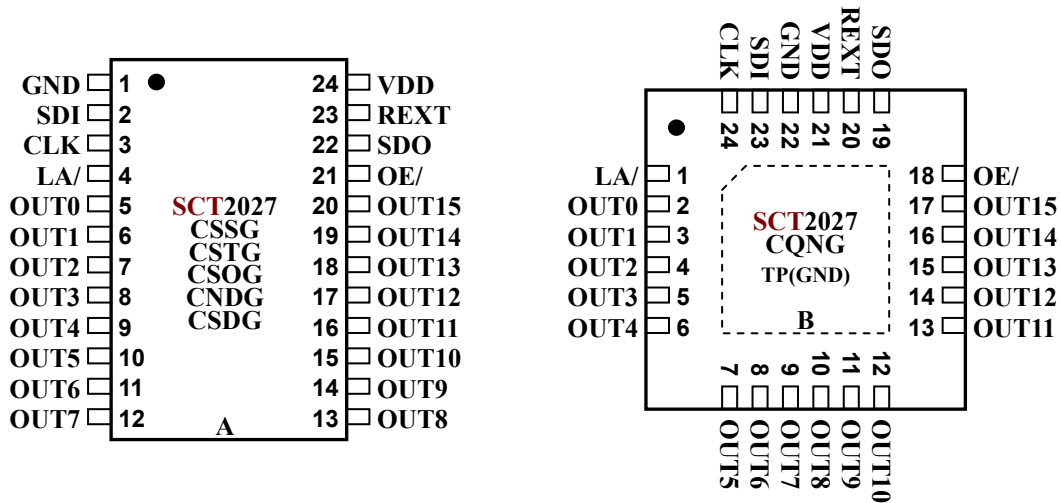
Since the high clock frequency can reach up to 25MHz, the SCT2027 satisfies the system requirements of high volume data transmission to control the LED display. The SCT2027 also guarantees each output endures up to 7V voltage stress, thus each output can drive multiple LEDs. The Modeless™ SCT2027 combines the error detection mechanism with display signals; hence the control unit does not need to switch between different modes, and therefore both the hardware costs and the control complexity can be reduced. In addition, the LED error status codes can be read in real time, and hence the fault status of the faulty LEDs can be discovered sooner.

*StarChips' patent protection.

Features

- ◆ Modeless™ On-the-fly error detection:
Directly Data-In Error-Out, without mode shifting and command configuration
- ◆ Seamless backward compatible with SCT2024, SCT2026, SCT2210:
Pin-to-pin package replacement without any PCB change
Timing control the same as standard Serial-In Parallel-Out interface
- ◆ Concurrent open/short detection without selection
- ◆ Shorter 200ns error detection time
- ◆ 16 robust constant current sinker with LED power-supply voltage up to 7V
- ◆ Constant output current : 3 – 50/90mA@3.3/5V
- ◆ Wide power supply voltages: 3.3V to 5V
- ◆ Excellent regulation to load, supply voltage and temperature
Temperature regulation: $\pm 0.005\%/^{\circ}\text{C}$,
Load regulation: $\pm 0.1\%/V$
Line regulation: $\pm 0.5\%/V$
- ◆ High current matching accuracy: $\pm 1\%$ between outputs, $\pm 2\%$ between ICs
- ◆ Fine grayscale response with 120ns PWM pulse width
- ◆ Dropout voltage 0.6V@60mA, $V_{DD}=5V$
- ◆ CMOS Schmitt trigger inputs with clock rate up to 25MHz @ cascade connection
- ◆ The constant current value of 16 outputs is set by a single external resistor
- ◆ Gradually 1.2ns delay of output, preventing instant current surge and output bouncing overstress
- ◆ Built-in power on reset(POR) circuit forces all the outputs off while power on
- ◆ Built-in thermal protection function to prevent damage from over current operation
- ◆ Package: SSOP24, SSOP24-1, SOP24, TQFN24, DIP24, and SDIP24
- ◆ Applications: LED Traffic Signs, LED Displays, Variable Message Signs, Illumination

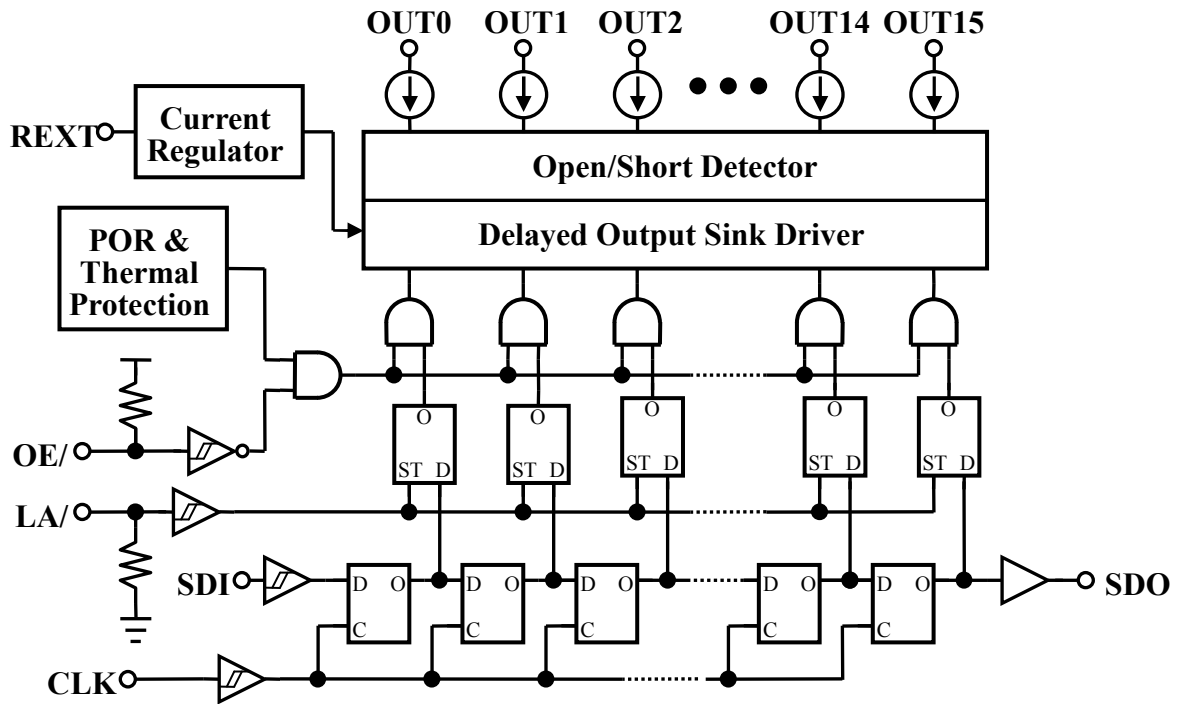
Pin Configurations



Terminal Description

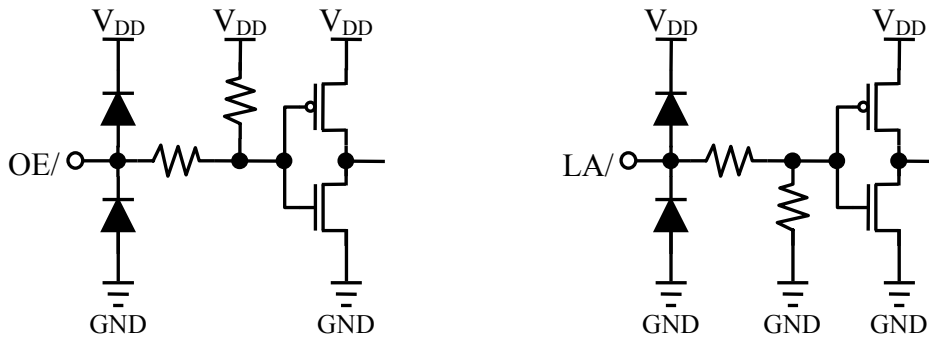
Pin Name	Pin No.		I/O	Function
	A	B		
GND	1	22 (TP)	-	Ground terminal(thermal pad included)
SDI	2	23	I	Serial input of data shift register.
CLK	3	24	I	Clock input of shift register, data is sampled at the rising edge of CLK.
LA/	4	1	I	Input terminal of data strobe. Data is latched when LA/ is low. Error detection is executed on rising edge of LA/
OUT[0:15]	5-20	2-17	O	Open-drain, constant-current outputs.
OE/	21	18	I	Output enable signal. Output is enabled when OE/ is forced to low.
SDO	22	19	O	Output terminal of serial-data output to the SDI of next SCT2027. Error code is read out at next data frame.
REXT	23	20	I/O	Used to connect an external resistor for setting up all output current
VDD	24	21	-	Supply voltage terminal

Block Diagram

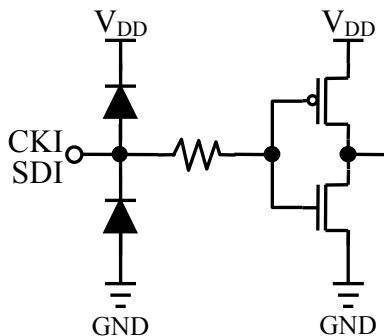


SCT2027

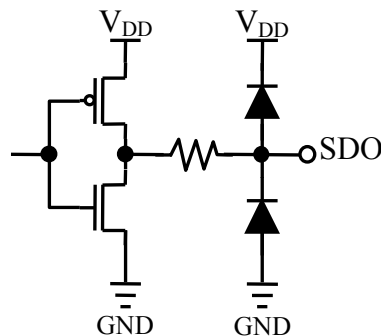
Equivalent Circuits of Inputs (1)



Equivalent Circuits of Inputs (2)



Equivalent Circuits of Output



Selector Guide

Part	Number of Outputs	Max Output Current (mA)	Min PWM Pulse Width (ns)	Supply Voltage (V)	Error Detection
SCT2110	8	180	100	5	NA
SCT2168	8	120	120	3.3/5	NA
SCT2169	8	120	120	3.3/5	Yes
SCT2167	8	60	180	3.3/5	NA
SCT2210	16	120	50	5	NA
SCT2026	16	90	120	3.3/5	NA
SCT2027	16	90	120	3.3/5	Yes
SCT2024	16	60	180	3.3/5	NA

Ordering Information

Part	Marking	Package	Unit per reel(pcs)
SCT2027CSSG	SCT2027CSSG	Green SSOP24	2500
SCT2027CSTG	SCT2027CSTG	Green SSOP24-1	2000
SCT2027CSOG	SCT2027CSOG	Green SOP24	1000
SCT2027CQNG	SCT2027CQNG	Green TQFN24	3000
SCT2027CNDG	SCT2027CNDG	Green DIP24	NA
SCT2027CSDG	SCT2027CSDG	Green SDIP24	NA

StarChips Technology, Inc.

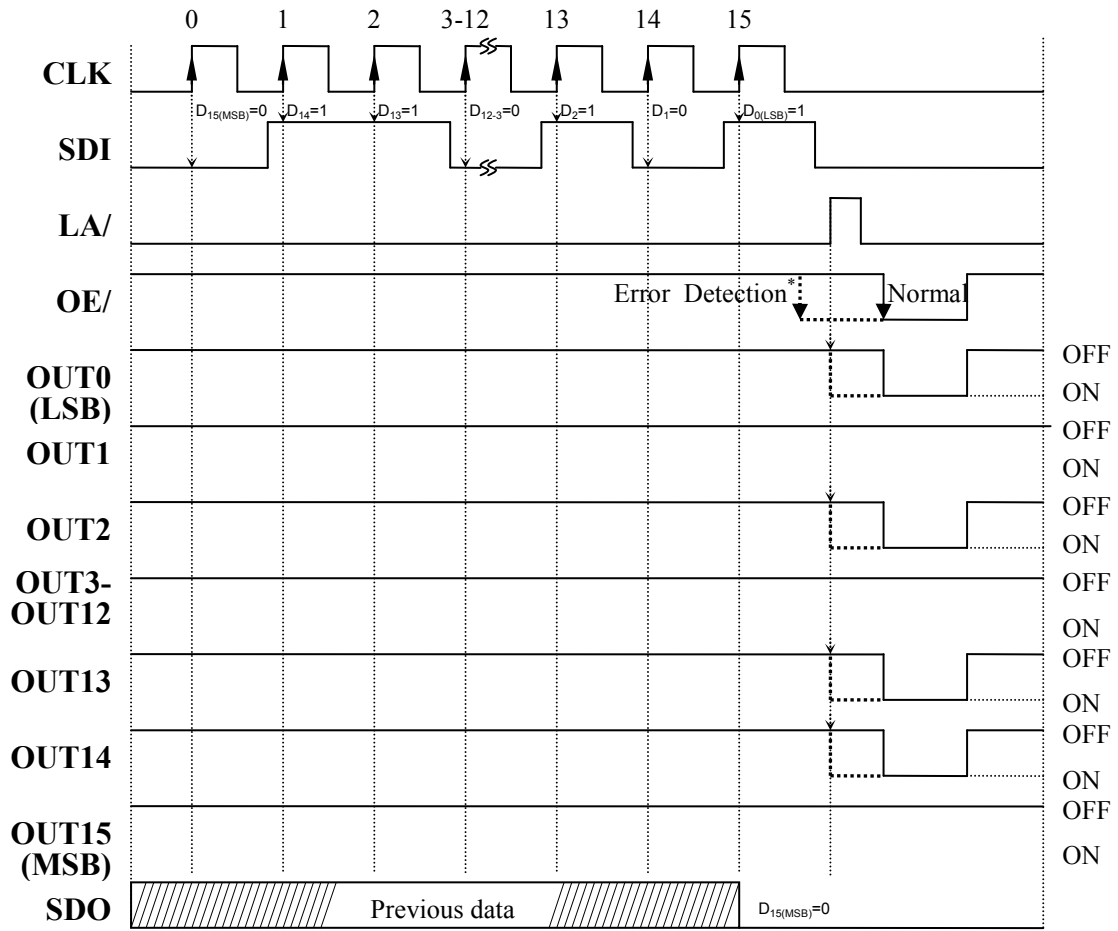
4F, No.5, Technology Rd., Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.

Tel : +886-3-577-5767 Ext.555

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E-mail : service@starchips.com.tw

Timing Diagram



*Note: The OE/ signal should be active before error checking.

Maximum Ratings (T_A = 25°C)

Characteristic		Symbol	Rating	Unit
Supply voltage		V _{DD}	7.0	V
Input voltage		V _{IN}	-0.2 ~ V _{DD} +0.2	V
Output current		I _{OUT}	90	mA/Channel
Output voltage	SDO	V _{OUT}	-0.2 ~ V _{DD} +0.2	V
	OUT0~OUT15		-0.2 ~ 7	V
Total GND terminals current		I _{GND}	1200	mA
Power dissipation	SOP24	P _D	1.92	W
	SSOP24		1.42	
	SSOP24-1.0		1.74	
	TQFN24		2.08	
	SDIP24		1.95	
	DIP24		2.27	
Thermal resistance	SOP24	R _{TH(j-a)}	65	°C/W
	SSOP24		88	
	SSOP24-1.0		72	
	TQFN24		60	
	SDIP24		64	
	DIP24		55	
Operating junction temperature		T _{J(max)}	150	°C
Operating temperature		T _{OPR}	-40~+85	°C
Storage temperature		T _{STG}	-55~+150	°C

The absolute maximum ratings are a set of ratings not to be exceeded. Stresses beyond those listed under “Maximum Ratings” may cause the device breakdown, deterioration even permanent damage. Exposure to the maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions (T_A= -40 to 85°C unless otherwise noted)

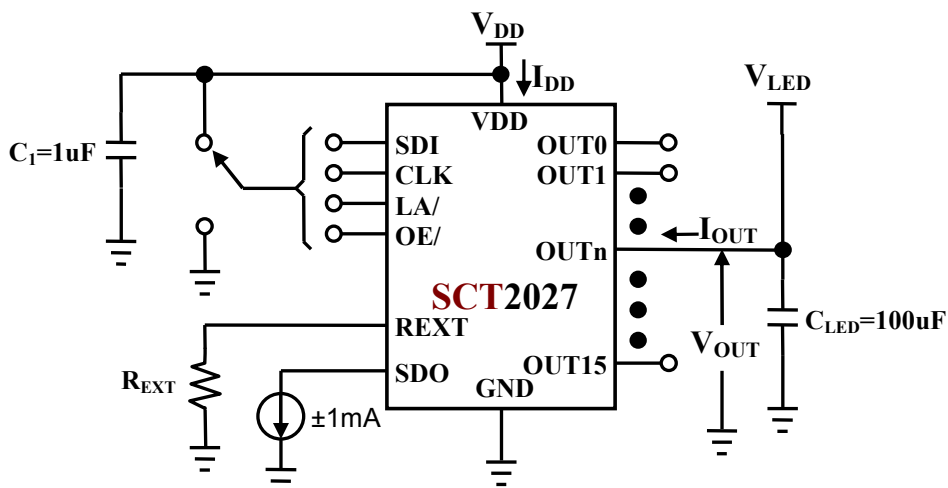
Characteristic	Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply voltage	V _{DD}	-	3	-	5.5	V
Output voltage (error code neglected)	V _{OUT}	Output OFF	-	-	7	V
		Output ON	-	1	4	V
Output voltage (error code acquired)	V _{OUT,ED}	Output OFF	-	-	V _{DD} -1.8	V
		Output ON	1.2	-	-	V
Output current	I _{OUT}	V _{DD} =3.3/5V	5	-	40/60	mA
Input voltage	V _{IH}	Input signals	0.7V _{DD}	-	V _{DD}	V
	V _{IL}	Input signals	0	-	0.3V _{DD}	V
OE/ pulse width	t _{W(OE)}	V _{DD} =3.3V/5V	120	-	-	ns
LA/ pulse width	t _{W(L,ED)}	Error detection	200	-	-	ns

Electrical Characteristics ($V_{DD}=3.3/5V$, $T_A=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Input voltage	V_{IH}	-	$0.7V_{DD}$	-	V_{DD}	V	
	V_{IL}	-	0	-	$0.3V_{DD}$	V	
SDO output voltage	V_{OH}	$V_{DD}=3.3/5V$, $I_{OH}=-1mA$	$V_{DD}-0.4$	-	-	V	
	V_{OL}	$V_{DD}=3.3/5V$, $I_{OL}=+1mA$	-	-	0.4	V	
Output leakage current	I_{OL}	$V_{OUT}=7V$	-	-	1	μA	
Output current	I_{OUT}	$V_{OUT}=1V$, $R_{EXT}=900\Omega$	-	21	-	mA	
Current bit skew ¹	dI_{OUT1}	$V_{OUT}=1V$, $R_{EXT}=900\Omega$	-	± 1	± 2	%	
Chip skew ²	dI_{OUT2}	$V_{OUT}=1V$, $R_{EXT}=900\Omega$	-	± 2	± 4	%	
Line regulation ³ I_{OUT} vs. V_{DD}	$\%/dV_{DD}$	$3V < V_{DD} < 5.5V$, $V_{OUT} > 1V$, $R_{EXT}=900\Omega$	-	± 0.5	± 1	%/V	
Load regulation ⁴ I_{OUT} vs. V_{OUT}	$\%/dV_{OUT}$	$1V < V_{OUT} < 4V$, $I_{OUT}=21mA$, $R_{EXT}=900\Omega$	-	± 0.1	± 0.5	%/V	
Temp. regulation ⁵ I_{OUT} vs. T_A	$\%/dT_A$	$-20^\circ C < T_A < 80^\circ C$, $I_{OUT}=5mA \sim 60mA$, $V_{DD}=5V$	-	± 0.005	-	%/°C	
Open threshold voltage	V_{OD}	-	-	0.8	1.2	V	
Short threshold voltage	V_{SD}	-	$V_{DD}-1.8$	$V_{DD}-1.6$	-	V	
Pull-up resistor	R_{UP}	OE/	-	500	-	K Ω	
Pull-down resistor	R_{DOWN}	LA/	-	500	-	K Ω	
Thermal shutdown	T_H	Junction Temp.	-	160	-	°C	
	T_L		-	110	-	°C	
Supply current	OFF	$I_{DD(OFF)1}$	$V_{DD}=3.3/5V$, $R_{EXT}=\text{Open}$, $OUT[0:15]=\text{OFF}$	-	3	4	mA
		$I_{DD(OFF)2}$	$V_{DD}=3.3/5V$, $R_{EXT}=900\Omega$, $OUT[0:15]=\text{ON}$	-	6	8	
	ON	$I_{DD(ON)}$	$V_{DD}=3.3/5V$, $R_{EXT}=900\Omega$, $OUT[0:15]=\text{ON}$	-	8/9	11	

1. Bit skew = $(I_{OUT} - I_{AVG}) / I_{AVG}$, where $I_{AVG} = (I_{OUT(max)} + I_{OUT(min)}) / 2$
2. Chip skew = $(I_{AVG} - I_{CEN}) / I_{CEN} * 100(\%)$, where I_{CEN} is the statistics distribution center of output currents.
3. Line regulation = $[I_{OUT}(V_{DD}=5.5V) - I_{OUT}(V_{DD}=3V)] / (5.5V - 3V) * 100(\%/V)$
4. Load regulation = $[I_{OUT}(V_{OUT}=4V) - I_{OUT}(V_{OUT}=1V)] / (4V - 1V) * 100(\%/V)$
5. Temperature regulation = $[I_{OUT}(T_A=80^\circ C) - I_{OUT}(T_A=-20^\circ C)] / (80^\circ C + 20^\circ C) * 100(\%/^\circ C)$

Test Circuit for Electrical Characteristics

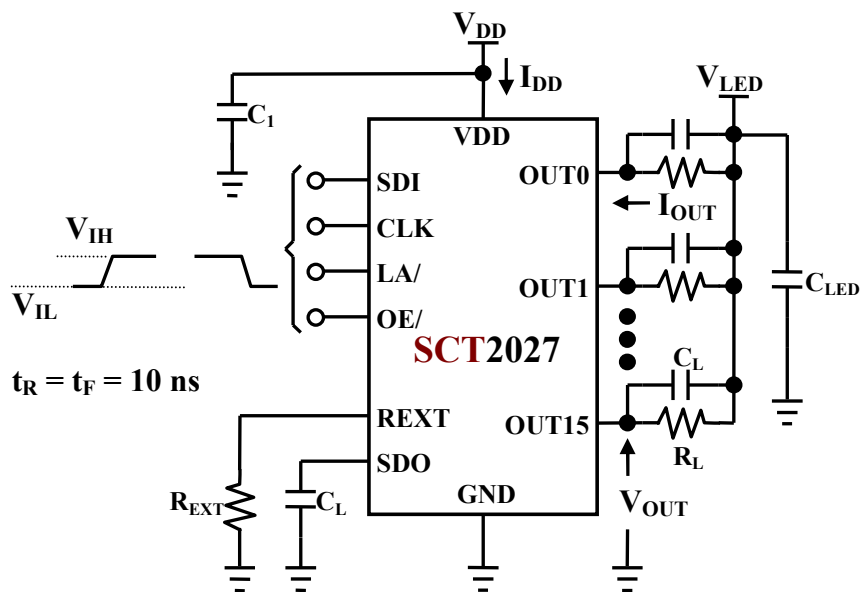


Switching Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Propagation delay time ("L" to "H")	CLK - OUTn	t_{PLH1}	-	60/40	80	ns	
	LA/ - OUTn	t_{PLH2}	-	60/40	80	ns	
	OE/ - OUT0	t_{PLH3}	-	60/40	60	ns	
	CLK - SDO	t_{PLH}	-	30/25	35	ns	
Propagation delay time ("H" to "L")	CLK - OUTn	t_{PHL1}	-	60/40	80	ns	
	LA/ - OUTn	t_{PHL2}	-	60/40	80	ns	
	OE/ - OUT0	t_{PHL3}	-	60/40	80	ns	
	CLK - SDO	t_{PHL}	-	30/25	35	ns	
Pulse width	CLK	$t_{W(CLK)}$	20/15	-	-	ns	
	LA/	$t_{W(L)}$	20	-	-	ns	
		$t_{W(L),ED}$	200	-	-	ns	
OE/	$t_{W(OE)}$	120	-	-	ns		
Setup time for SDI	$t_{S(D)}$	$V_{DD} = 3.3/5\text{V}$ $V_{LED} = 5\text{V}$ $V_{IH} = V_{DD}$ $V_{IL} = \text{GND}$ $R_{EXT} = 900\Omega$ $R_L = 180\Omega$ $C_L = 10\text{pF}$ $C_1 = 1\mu\text{F}$ $C_{LED} = 100\mu\text{F}$	3	-	-	ns	
Hold time for SDI	t_{HD}		5	-	-	ns	
Setup time for LA/	$t_{S(L)}$		5	-	-	ns	
Hold time for LA/	$t_{H(L)}$		5	-	-	ns	
SDO rise time	t_{SDOR}		-	10	-	ns	
SDO fall time	t_{SDOF}		-	10	-	ns	
Output rise time of I_{OUT}	t_{OR}		-	35	50	ns	
Output fall time of I_{OUT}	t_{OF}		-	35	50	ns	
Delayed output	t_{DR}		OUTn to OUTn+1	-	1.2	-	ns
	t_{DF}			-	1.2	-	ns
Slow CLK rise time ¹	t_R		Cascade	-	-	500	ns
Slow CLK fall time	t_F			-	-	500	ns

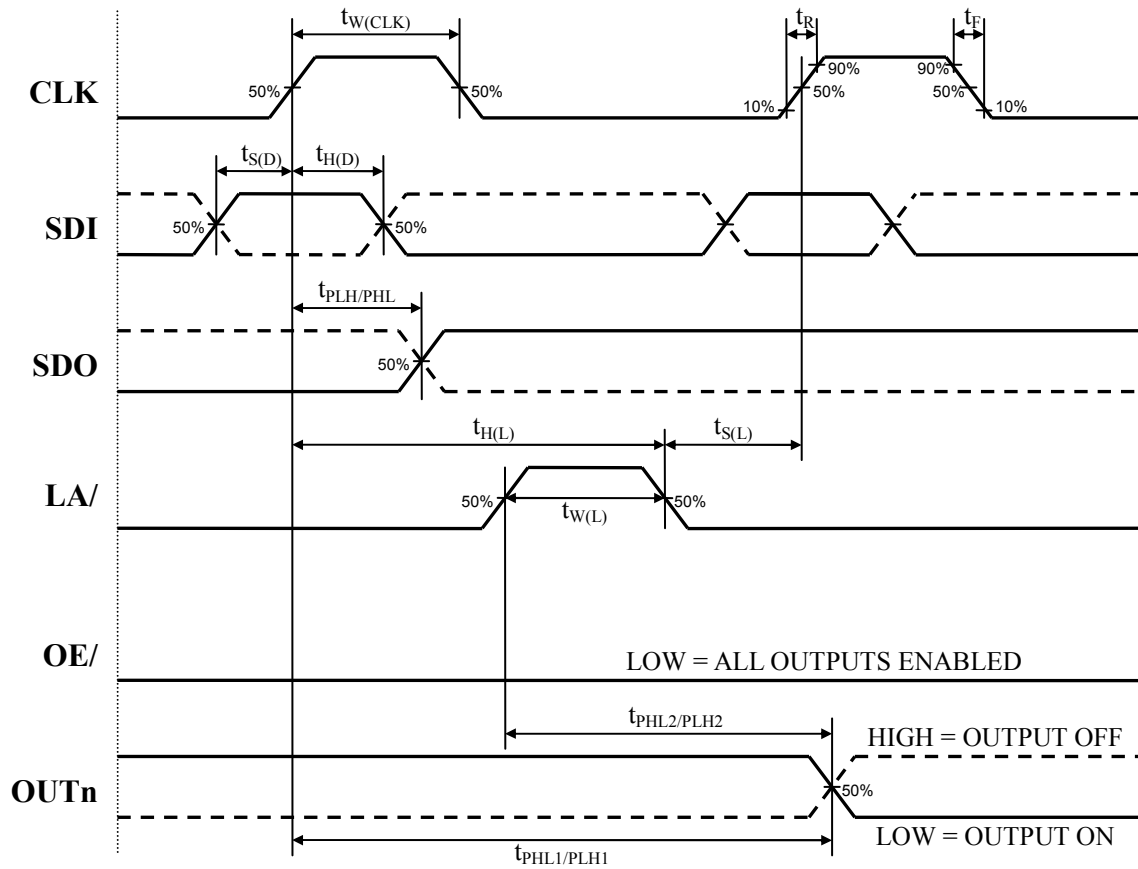
1. It may not be possible to achieve the timing requirement for data transfer if t_R and t_F is too large during cascaded operation.

Test Circuit for Switching Characteristics

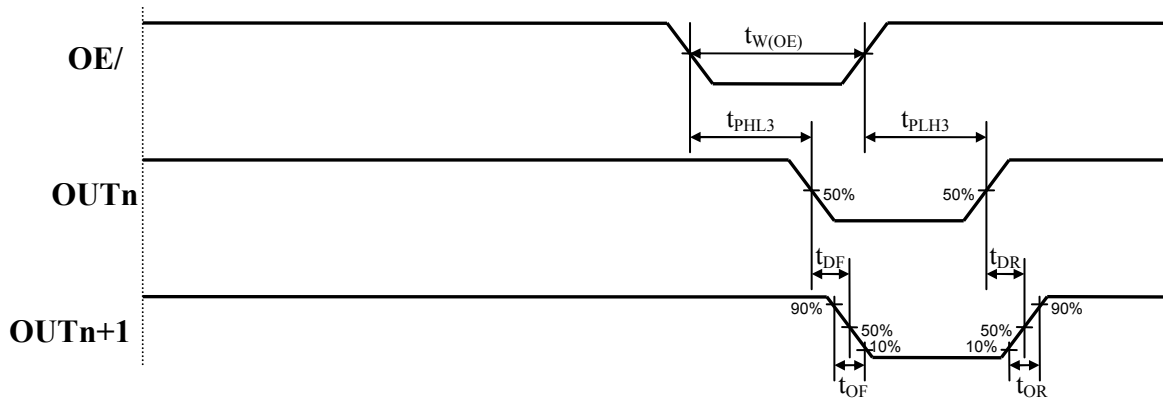


Timing Waveform

LA/ Control Output

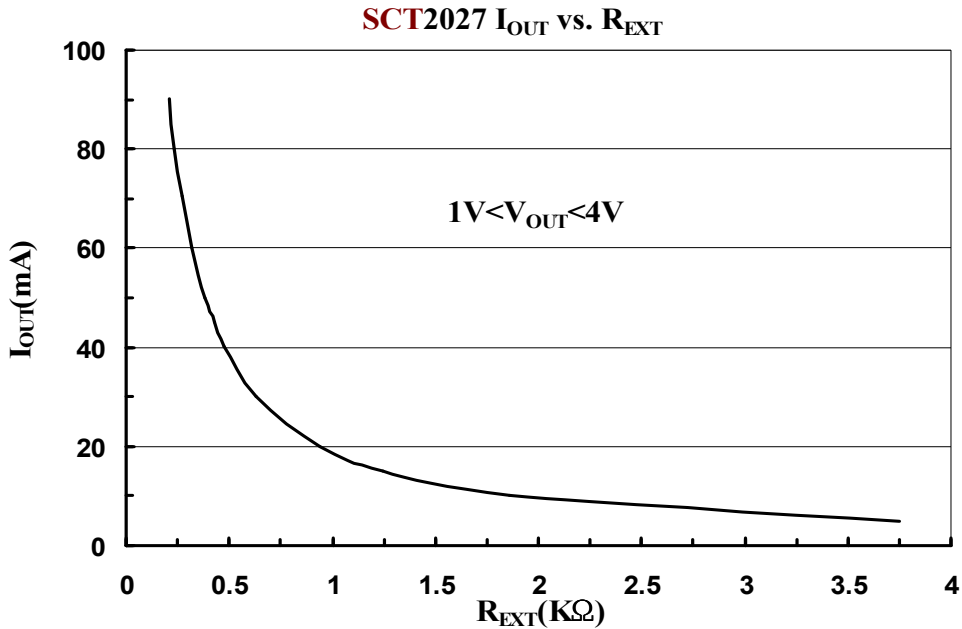


OE/ Control Output



Adjusting Output Current

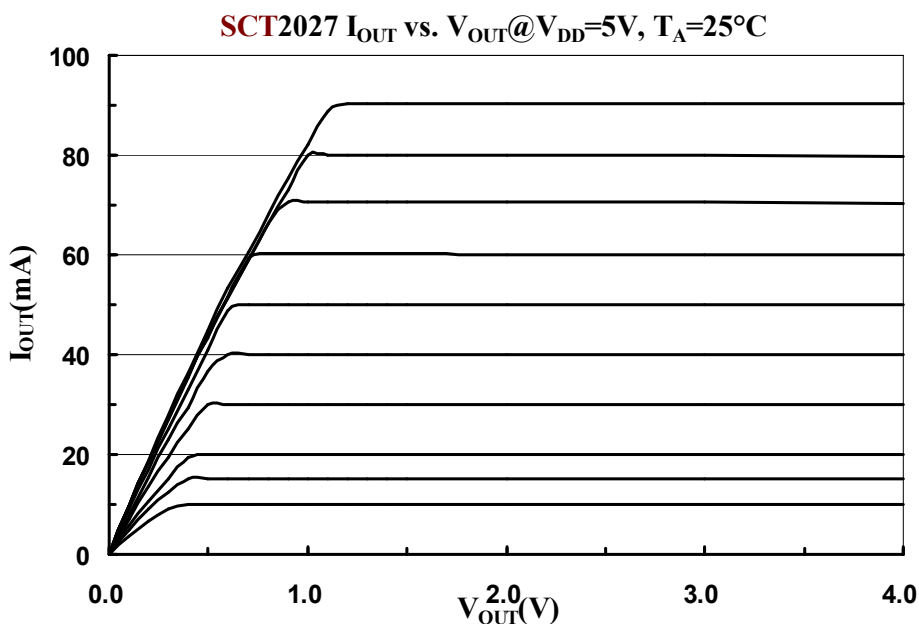
The SCT2027's output current (I_{OUT}) are set by one external resistor at pin REXT. The output current I_{OUT} versus resistance of R_{EXT} is shown as the following figure.



Furthermore, when SCT2027's output voltage is set between 1 Volt and 4 Volt, the output current can be estimated approximately by: $I_{OUT} = 30(630 / R_{EXT})$ (mA) (chip skew < $\pm 4\%$). Thus the output current are set about 21mA at $R_{EXT} = 900\Omega$.

Output Characteristics

The current characteristic of output curve is flat. The output current can be kept constant regardless of the variations of LED forward voltage when $V_{OUT} > 1V$. The relationship between I_{OUT} and V_{OUT} is shown below.



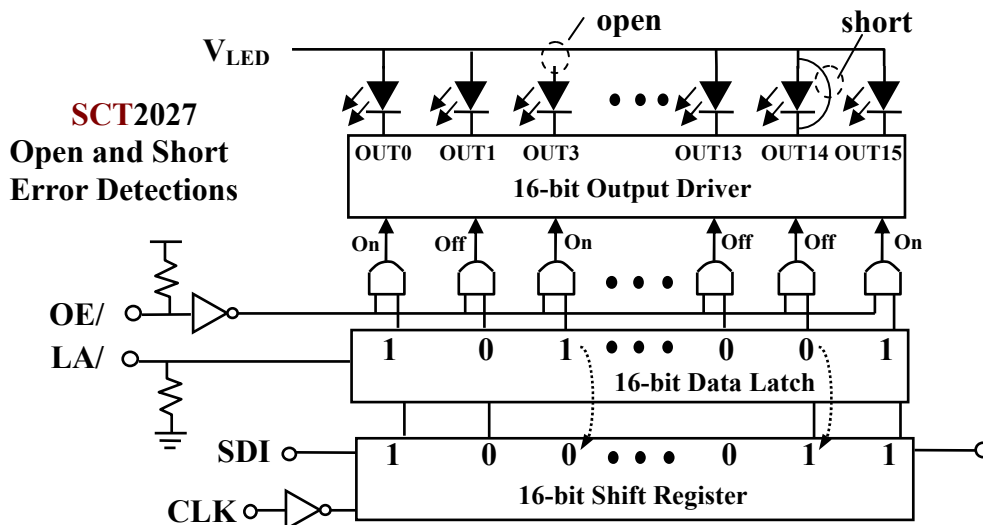
Error Detection

The SCT2027 acts fully the same as the SCT2024/6, simply latching data and driving the outputs. Also, the SCT2027 performs the Modeless™ error-detection function while driving the outputs. When display data are written into the SCT2027, the SCT2027 uses them to drives the outputs and checks each output status. If the output status is good, the bit '1' turns on the output and the bit '0' turns off the output. The SCT2027 detects the open error for bit '1' and the short error for bit '0'. The SCT2027 reports an open error by changing bit '1' into bit '0' and it reports a short error by overwriting bit '0' into bit '1'. When new display data continue to be written into the SCT2027, the error messages can be read from pins of SDO without changing any display data and operating mode.

Once the error-detection function is active, functions of open and short circuit detection are executed accompanying with LEDs' lights up or not. When data bits of latch are '1' and the OE/ pulse width is large than 120ns, the SCT2027 lights up LEDs and checks their open status. The SCT2027 updates bits of '1' of shift register with '0' at the moment when open-load errors are found. On the other hand, when data bits of latch are '0', the SCT2027 turns off LEDs, checks the 'short' status. Contents of the shift register will be changed from '0' to '1' if short-load errors are detected. Execution of error-detection does not affect any data or message of the LED display.

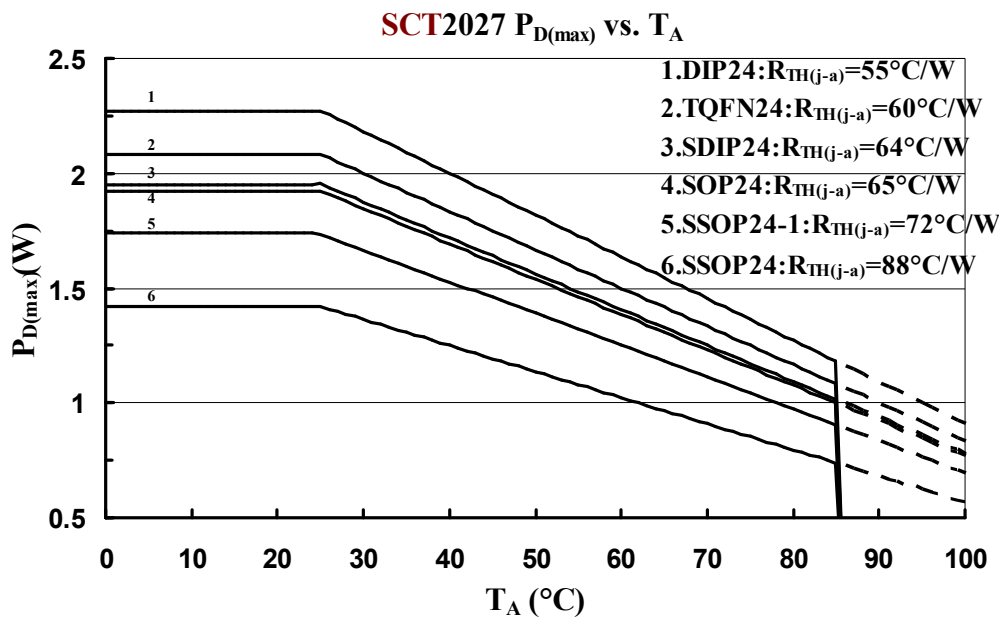
Since the error status is determined by comparing the output voltage value with the short and open threshold voltages, the operating output voltage should be set to be larger than 1.2V and less than $V_{DD}-1.8V$ for accurate results of error checking.

Also, the OE/ signal should be active before error checking and the LA/ pulse width must be larger than 200ns, which is considered to be adequate to get a settled output voltage when checked by the internal circuits.



Power Dissipation

The maximum power dissipation ($P_{D(max)}$) of a semiconductor chip varies with different packages and ambient temperature. It's determined as $P_{D(max)} = (T_{J(max)} - T_A) / R_{TH(j-a)}$ where $T_{J(max)}$: maximum chip junction temperature is usually considered as 150°C, T_A : ambient temperature, $R_{TH(j-a)}$: thermal resistance. Since $P=IV$, for sink larger I_{OUT} , users had better add proper voltage reducers on outputs to reduce the heat generated from the SCT2027.

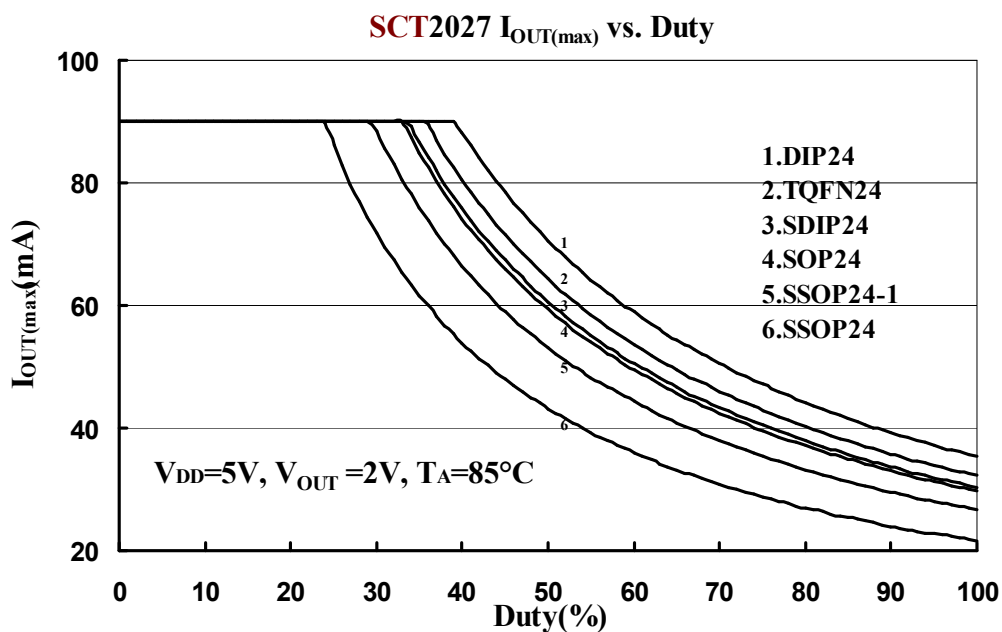


Limitation on Maximum Output Current

The maximum output current vs. duty cycle is estimated by:

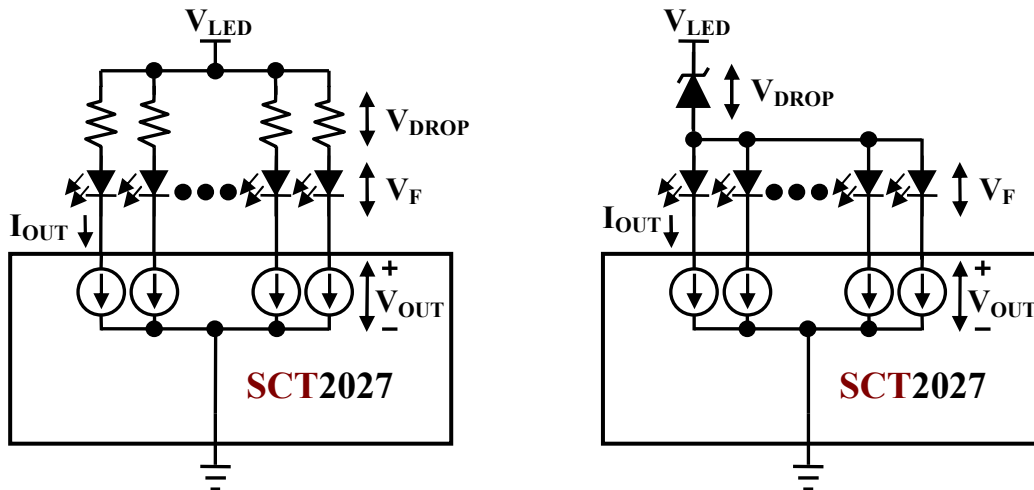
$$I_{OUT(max)} = (((T_{J(max)} - T_A) / R_{TH(j-a)}) - (V_{DD} * I_{DD})) / V_{OUT} / \text{Duty} / N$$

where $T_{J(max)} = 150^\circ\text{C}$, $N = 16$ (all ON)



Load Supply Voltage (VLED)

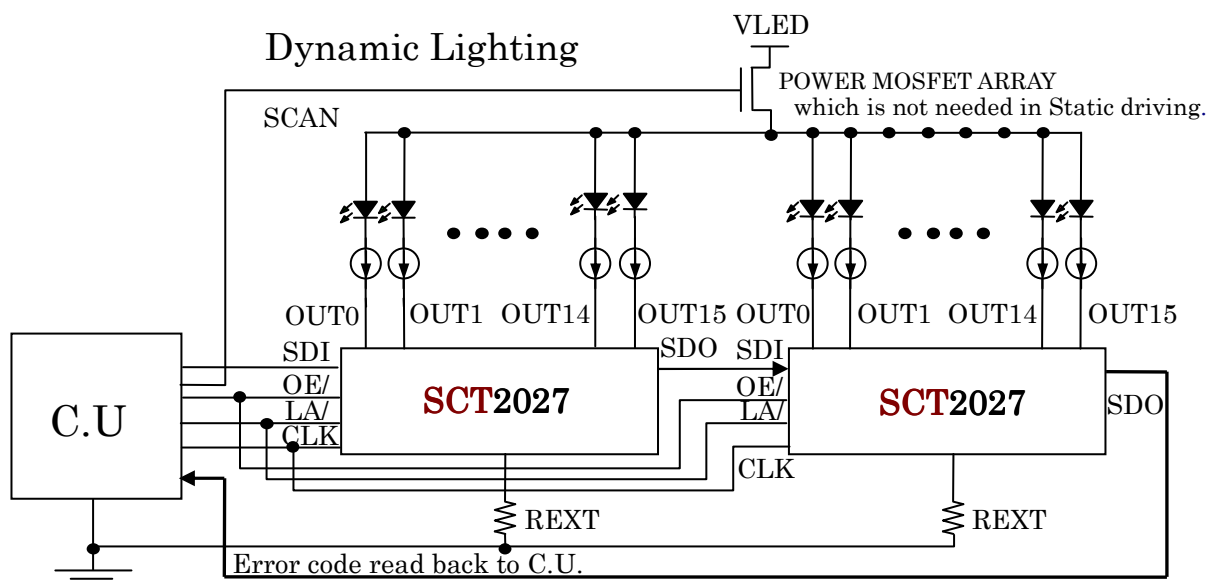
The SCT2027 can be operated very well when V_{OUT} ranges from 1V to 4V. It is recommended to use the lowest possible supply voltage or set a voltage reducer to reduce the V_{OUT} voltage, at the same time reduce the power dissipation of the SCT2027. This can prevent the IC from malfunction with thermal shutdown situation. Follow the diagram instructions shown below to lower down the output voltage. This can be done by adding additional resistor or zener diode, thus $V_{OUT} = V_{LED} - V_{DROP} - V_F$.



Over Temperature Shutdown

The SCT2027 contains thermal shutdown scheme to prevent damage from over-heating. The internal thermal sensor turns off all outputs when the die temperature exceeds +160°C. The outputs are enabled again when the die temperature drops below +110°C. During the thermal shutdown process, the LEDs look blinking since it is turned OFF then ON periodically.

Typical Application Circuits

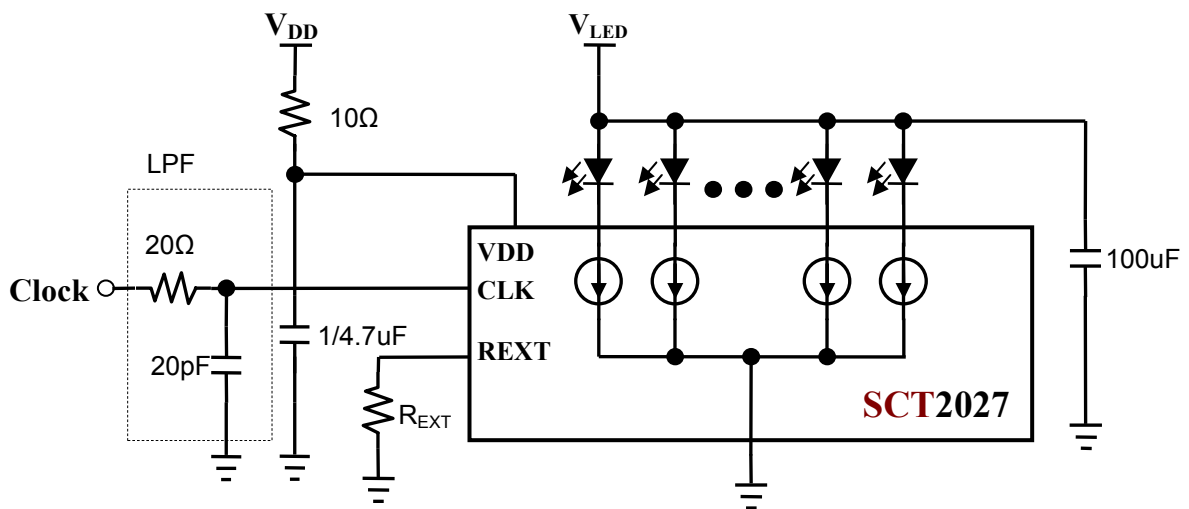


PCB Design Considerations

Use the following general guide-line when designing printed circuit boards (PCB):

Decoupling Capacitor

Place a decoupling capacitor e.g. 1uF between VDD and GND pins of SCT2027. Locate the capacitor as close to the SCT2027 as possible. This is normally adequate for static LED driving. For dynamic scan or PWM applications, it is necessary to add an additional capacitor of 4.7uF or more to each supply for every SCT2027. The necessary capacitance depends on the LED load current, PWM switching frequency, and serial-in data speed. Inadequate VDD decoupling can cause timing problems, and very noisy LED supplies can affect LED current regulation.



External Resistor (R_{EXT})

Locate the external resistor as close to the REXT pin as possible to avoid the noise influence.

Power and Ground

Maximizing the width and minimizing the length of VDD and GND trace improves efficiency and ground bouncing by effect of reducing both power and ground parasitic resistance and inductance. A small value of resistor e.g. 10Ω series in power input of the SCT2027 in conjunction with decoupling capacitor shunting the IC is recommended. Separating and feeding the LED power from another stable supply terminal V_{LED} , furthermore adding a larger capacitor e.g. 100uF beside the LED are strongly recommended.

EMI Reduction

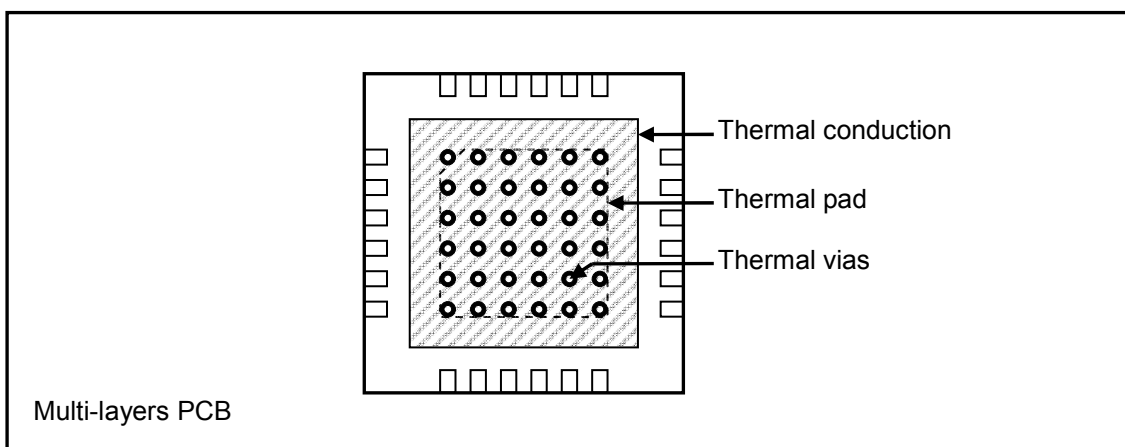
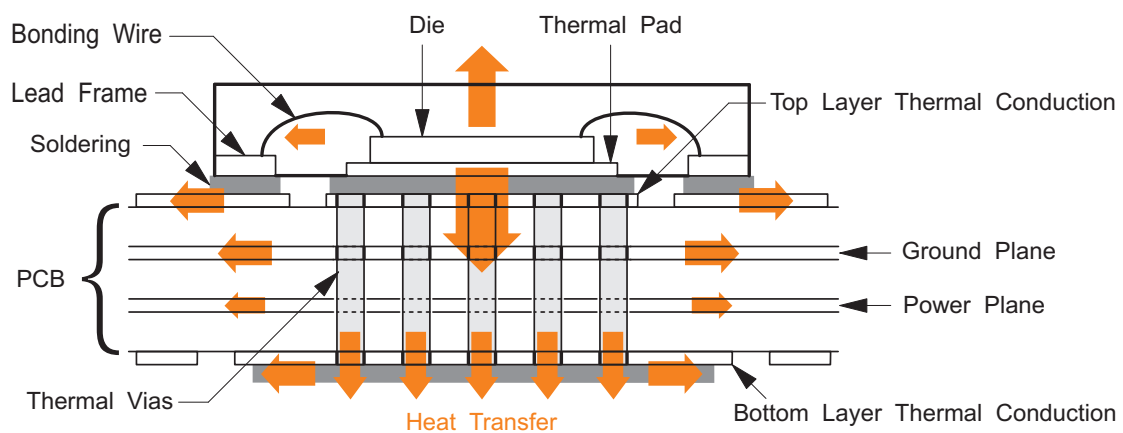
To reduce the EMI radiation from system, an economic solution RC low pass filter (LPF) is suggested to be used to lower the transient edge of clock input signal, as shown in the figure above. Using at least four layers PCB board with two interior power and ground planes is a good scheme to decrease the signal current path which is the source of radiation emission. As a result, EMI radiation can be decreased.

Thermal Pad Consideration

The “thermal pad” (also named as “exposed pad”) TQFN24 package beneath is wire-bonded to pin 22(GND) ground terminal internally. User should be aware of this electrical connection when designing the PCB board, and make provisions for its use.

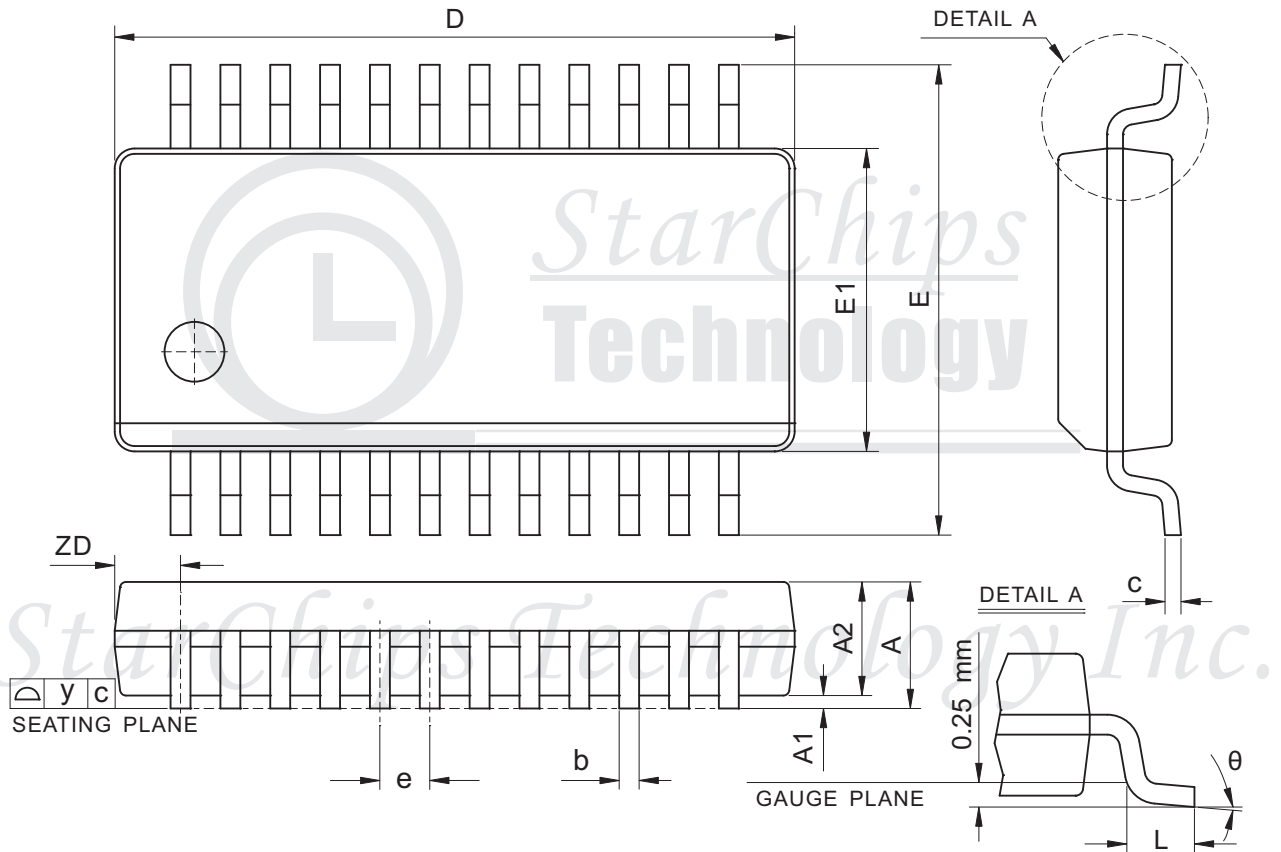
In general, the heat generated from an IC is conducted to the PCB then radiates to the ambient. Thermal pad specifically increases the maximum power dissipation capability of the IC packages. To provide lower thermal resistance from the IC to the ambient air, PCB designers should layout larger thermal conduction areas on top layer (component side) and bottom layer (solder side) as well as thermal vias, the more the better. In addition, connecting thermal via to the ground plane also increases thermal conduction areas, this improves the heat transfer efficiency at the same time greatly dissipates heat generated from the package. Furthermore, coating solder on bottom layer and selecting e.g. 2 oz. copper which will increase the total thickness of thermal conduction is an alternative.

When making the solder paste screen, an opening should be created for the thermal pad. This way the thermal pad can be electrically and thermally connected to the PCB. As the thermal pad is soldered on copper polygon, the chance of inadvertently shorting the thermal pad to traces routed underneath it could be eliminated.



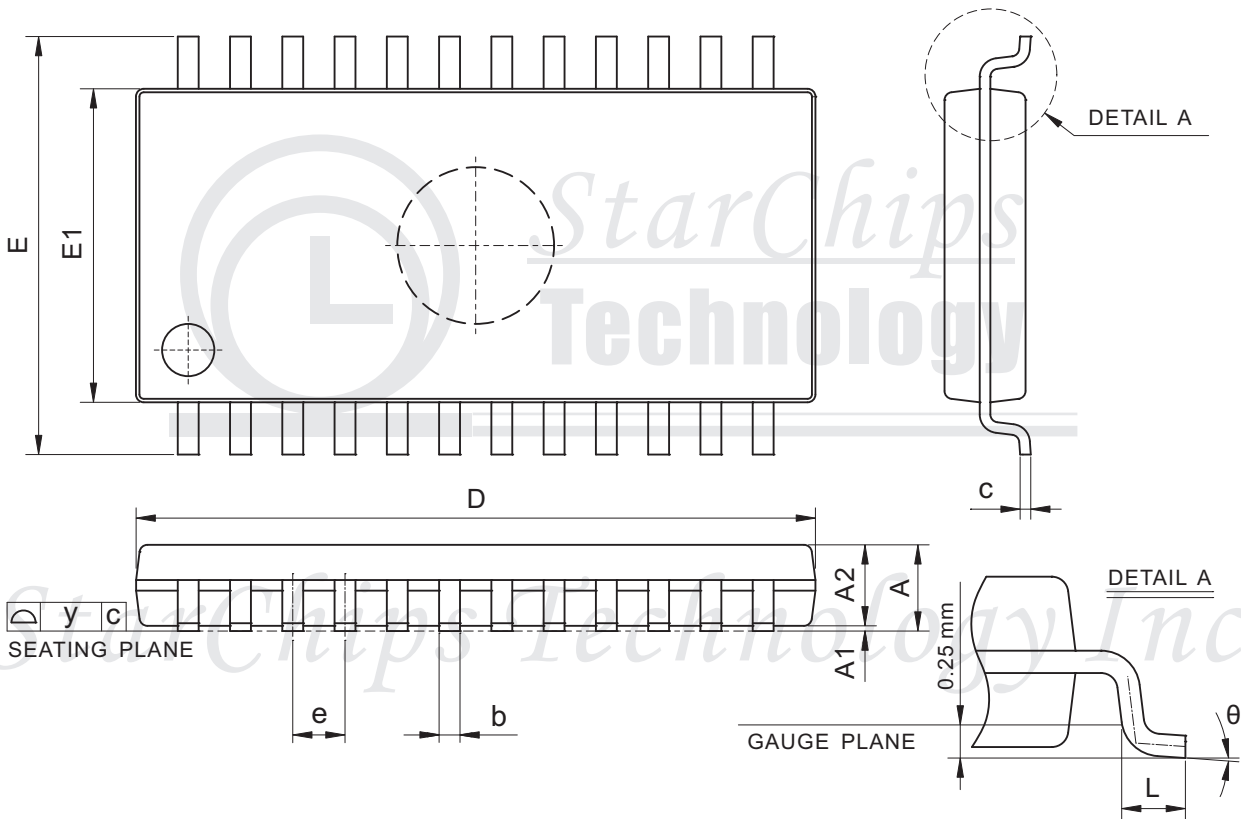
Package Dimension

SSOP24([check up-to-date version](#))



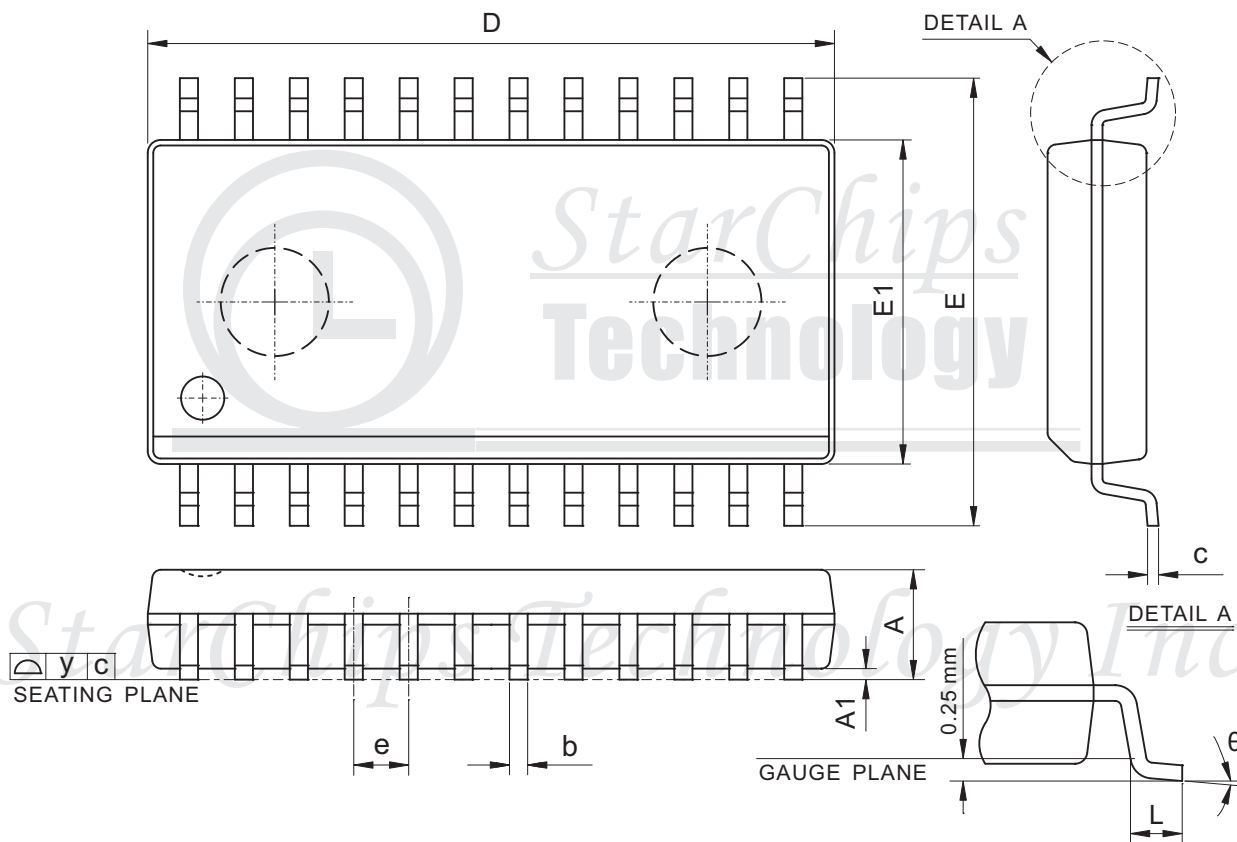
Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	1.35	1.63	1.75	53.1	64.2	68.9
A1	0.10	0.15	0.25	3.9	5.9	9.8
A2	-	-	1.50	-	-	59.1
b	0.20	-	0.30	7.9	-	11.8
c	0.18	-	0.25	7.1	-	9.8
D	8.56	8.66	8.74	337.0	340.9	344.1
E	5.79	5.99	6.20	228.0	235.8	244.1
E1	3.81	3.91	3.99	150.0	153.9	157.1
e	0.64 BSC			25.0 BSC		
L	0.41	0.64	1.27	16.1	25.0	50.0
y	-	-	0.10	-	-	3.9
ZD	0.84 REF			33.0 REF		
theta	0°	-	8°	0°	-	8°

SSOP24-1 ([check up-to-date version](#))



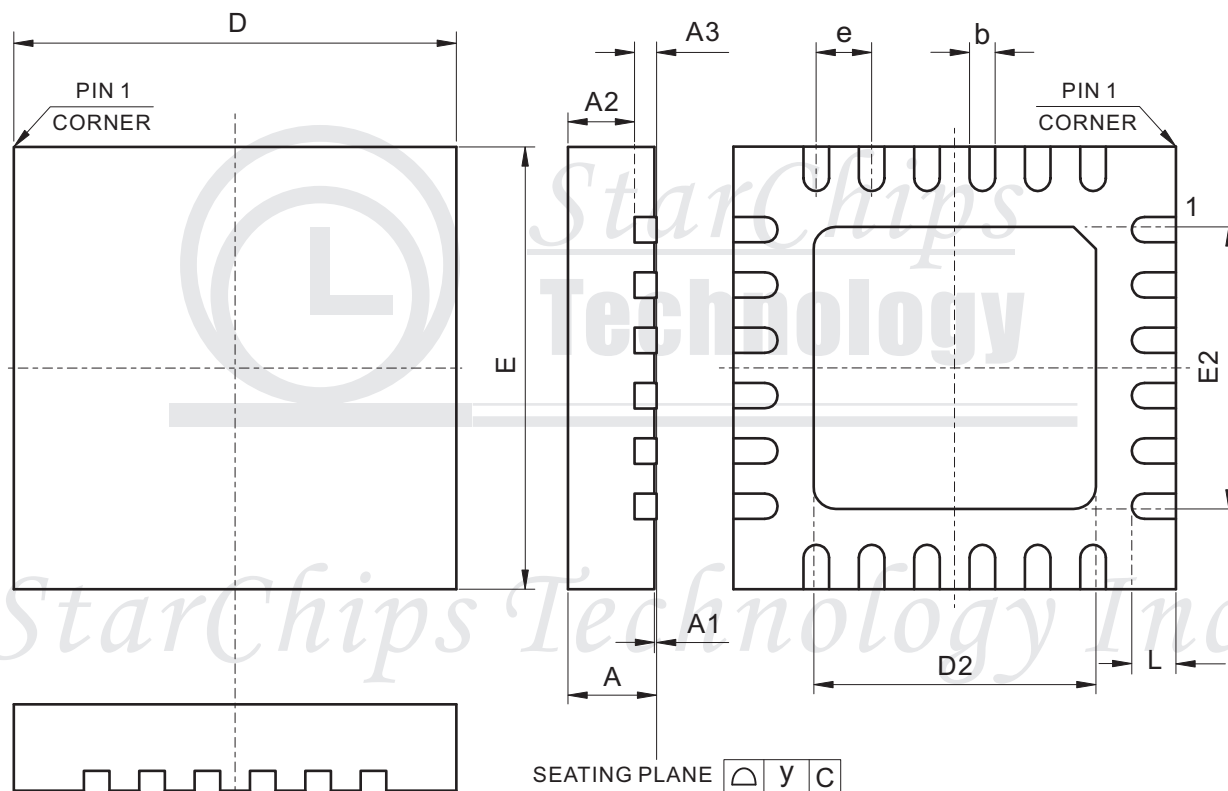
Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.90	-	-	74.8
A1	0.05	0.10	0.15	2.0	3.9	5.9
A2	1.30	1.50	1.70	51.2	59.1	66.9
b	0.30	0.40	0.52	11.8	15.7	20.5
c	0.10	0.15	0.27	3.9	5.9	10.6
D	12.80	13.00	13.20	503.9	511.8	519.7
E	7.70	8.00	8.30	303.1	315.0	326.8
E1	5.80	6.00	6.20	228.3	236.2	244.1
e	1.00 BSC			39.4 BSC		
L	0.25	0.45	0.65	9.8	17.7	25.6
y	-	-	0.10	-	-	3.9
θ	0°	-	10°	0°	-	10°

SOP24([check up-to-date version](#))



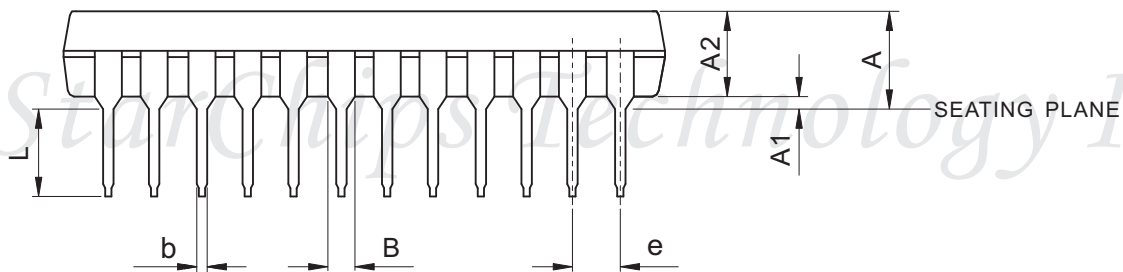
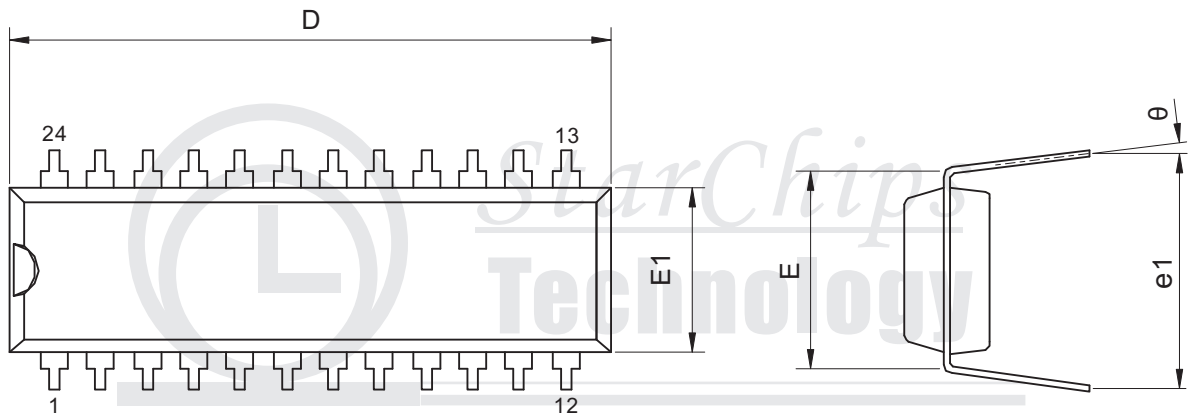
Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	2.35	-	2.65	92.5	-	104.3
A1	0.10	-	0.30	3.9	-	11.8
b	0.33	-	0.51	13.0	-	20.1
c	0.23	-	0.32	9.1	-	12.6
D	15.20	-	15.60	598.4	-	614.2
E	10.00	-	10.65	393.7	-	419.3
E1	7.40	-	7.60	291.3	-	299.2
e	1.27 BSC			50.0 BSC		
L	0.40	-	1.27	15.7	-	50.0
θ	0°	-	8°	0°	-	8°
y	-	-	0.10	-	-	3.9

TQFN24-4x4([check up-to-date version](#))



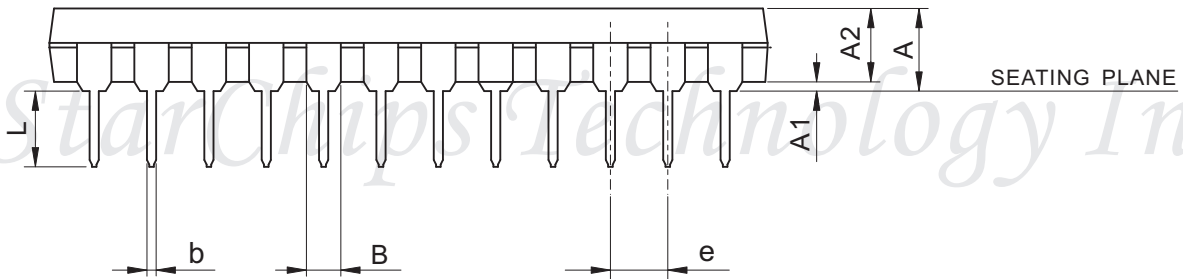
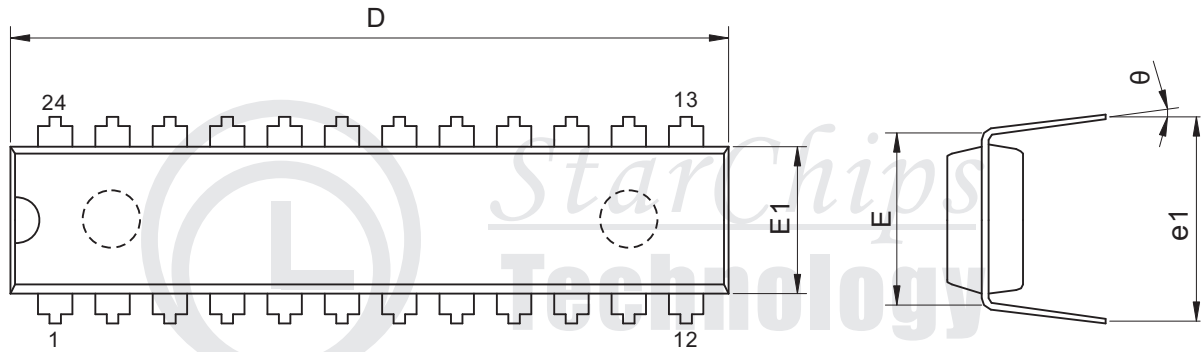
Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.76	0.80	0.84	30.0	31.0	33.0
A1	0.00	0.02	0.04	0.0	0.8	1.5
A2	0.57	0.60	0.63	22.0	24.0	25.0
A3	0.20 REF			8.0 REF		
b	0.18	0.25	0.30	7.1	9.8	11.8
D	3.90	4.00	4.10	154.0	157.0	161.0
D2	2.50	2.55	2.60	98.4	100.4	102.4
E	3.90	4.00	4.10	154.0	157.0	161.0
E2	2.50	2.55	2.60	98.4	100.4	102.4
e	0.50 BSC			19.7 BSC		
L	0.35	0.40	0.45	13.8	15.7	17.7
y	-	0.08	-	-	3.1	-

SDIP24([check up-to-date version](#))



Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	5.33	-	-	210.0
A1	0.38	-	-	15.0	-	-
A2	3.18	3.30	3.43	125.0	130.0	135.0
b	-	0.46	-	-	18.0	-
B	-	1.02	-	-	40.0	-
e	-	1.78	-	-	70.0	-
D	22.35	22.86	23.37	880.0	900.0	920.0
E	-	7.62	-	-	300.0	-
E1	6.22	6.35	6.48	245.0	250.0	255.0
e1	8.51	9.02	9.53	335.0	355.0	375.0
L	2.92	3.30	3.81	115.0	130.0	150.0
θ	0°	7°	15°	0°	7°	15°

DIP24([check up-to-date version](#))



Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	5.33	-	-	210.0
A1	0.38	-	-	15.0	-	-
A2	3.18	3.30	3.43	125.0	130.0	135.0
b	-	0.46	-	-	18.0	-
B	-	1.52	-	-	60.0	-
e	-	2.54	-	-	100.0	-
D	31.24	31.75	32.51	1230.0	1250.0	1280.0
E	-	7.62	-	-	300.0	-
E1	6.43	6.55	6.68	253.0	258.0	263.0
e1	8.51	9.02	9.53	335.0	355.0	375.0
L	2.92	3.30	3.81	115.0	130.0	150.0
θ	0°	7°	15°	0°	7°	15°

Revision History([check up-to-date version](#))

Data Sheet Version	Remark
V01_02	Updated

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